





### SURFACE MOUNT SCHOTTKY BARRIER DIODE

### **Features**

- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Leadless Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

## **Mechanical Data**

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Bar
- Terminals: Finish NiPdAu Annealed over Copper Leadframe.
  Solderable per MIL-STD-202, Method 208 €
- Weight: 0.001 grams (Approximate)

### X1-DFN1006-2





Top View

**Bottom View** 

## **Ordering Information** (Note 4)

| Part Number | Case         | Packaging          |
|-------------|--------------|--------------------|
| BAT54LP-7   | X1-DFN1006-2 | 3,000/Tape & Reel  |
| BAT54LP-7B  | X1-DFN1006-2 | 10,000/Tape & Reel |

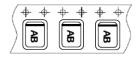
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**



| L1



Top View

Top View

Bar Denotes Cathode Side

L1 or  $\overline{L}1$  = Product Type Marking Code Bar Denotes Cathode Side



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic   |            | Symbol                                | Value | Unit |
|--|------------|---------------------------------------|-------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage |            | V <sub>RRM</sub><br>V <sub>R</sub> wm | 30    | ٧    |
| Forward Continuous Current   |            | I <sub>F</sub>                        | 200   | mA   |
| Repetitive Peak Forward Current  |            | I <sub>FRM</sub>                      | 300   | mA   |
| Forward Surge Current  | @ t < 1.0s | I <sub>FSM</sub>                      | 600   | mA   |

### **Thermal Characteristics**

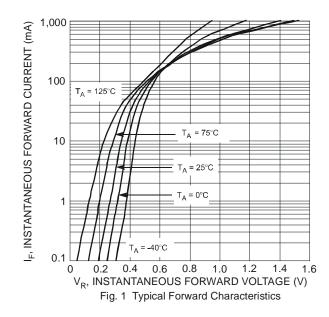
| Characteristic                                       | Symbol                            | Value       | Unit |
|--|-----------------------------------|-------------|------|
| Power Dissipation (Note 5)                           | P <sub>D</sub>                    | 250         | mW   |
| Thermal Resistance, Junction to Ambient Air (Note 5) | $R_{	hetaJA}$                     | 400         | °C/W |
| Operating and Storage Temperature Range              | T <sub>J</sub> , T <sub>STG</sub> | -65 to +125 | °C   |

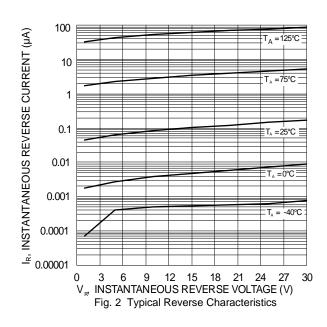
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                     | Symbol             | Min | Тур | Max                               | Unit | Test Condition   |
|------------------------------------|--------------------|-----|-----|-----------------------------------|------|--|
| Reverse Breakdown Voltage (Note 6) | V <sub>(BR)R</sub> | 30  | _   | _                                 | V    | $I_R = 100 \mu A$  |
| Forward Voltage                    | VF                 | _   | _   | 240<br>320<br>400<br>500<br>1,000 | mV   | I <sub>F</sub> = 0.1mA<br>I <sub>F</sub> = 1mA<br>I <sub>F</sub> = 10mA<br>I <sub>F</sub> = 30mA<br>I <sub>F</sub> = 100mA |
| Reverse Leakage Current (Note 6)   | I <sub>R</sub>     | _   | _   | 2.0                               | μA   | V <sub>R</sub> = 25V   |
| Total Capacitance                  | CT                 | _   | _   | 10                                | pF   | $V_R = 1.0V, f = 1.0MHz$   |
| Reverse Recovery Time              | t <sub>RR</sub>    | _   | _   | 5.0                               | ns   | $I_F = 10$ mA through $I_R = 10$ mA<br>to $I_R = 1.0$ mA, $R_L = 100$ Ω  |

Notes:

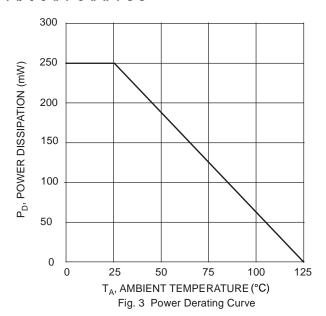
<sup>6.</sup> Short duration pulse test used to minimize self-heating effect.





<sup>5.</sup> Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.

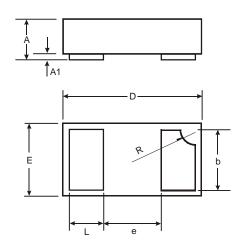




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X1-DFN1006-2

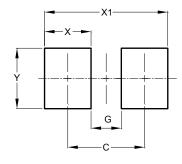


| X1-DFN1006-2         |      |       |      |  |
|----------------------|------|-------|------|--|
| Dim                  | Min  | Max   | Тур  |  |
| Α                    | 0.47 | 0.53  | 0.50 |  |
| A1                   | 0    | 0.05  | 0.03 |  |
| b                    | 0.45 | 0.55  | 0.50 |  |
| D                    | 0.95 | 1.075 | 1.00 |  |
| Е                    | 0.55 | 0.675 | 0.60 |  |
| е                    | -    | -     | 0.40 |  |
| L                    | 0.20 | 0.30  | 0.25 |  |
| R                    | 0.05 | 0.15  | 0.10 |  |
| All Dimensions in mm |      |       |      |  |

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X1-DFN1006-2



| Dimensions | Value<br>(in mm) |  |  |
|------------|------------------|--|--|
| C          | 0.70             |  |  |
| G          | 0.30             |  |  |
| Х          | 0.40             |  |  |
| X1         | 1.10             |  |  |
| Y          | 0.70             |  |  |



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